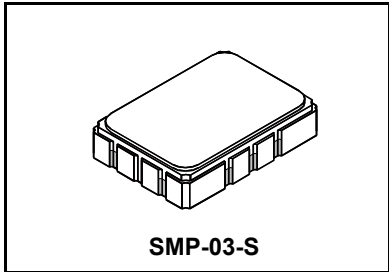


- *Designed for SDARS IF Receiver*
- *Low Insertion Loss*
- *5.0 X 7.0 mm Surface-Mount Case*
- *Differential Input and Output*
- *Complies with Directive 2002/95/EC (RoHS)*



**SF1143B-4**

**315.00 MHz  
SAW Filter**



**Absolute Maximum Ratings**

Rating	Value	Units
Maximum Incident Power in Passband	+10	dBm
Max. DC voltage between any 2 terminals	30	VDC
Storage Temperature Range	-40 to +85	°C
Max Soldering Profile	265°C for 10 s	

**Electrical Characteristics**

Characteristic	Sym	Notes	Min	Typ	Max	Units
Nominal Center Frequency	$f_C$	1	315.000			MHz
Passband Insertion Loss at $f_C$ 1dB Passband	IL	1, 2		15.1	17.0	dB
	$BW_1$		$\pm 6.35$	$\pm 7.05$		MHz
Fast Amplitude Ripple over $f_C \pm 6.35$ MHz		1, 2			1.5	dB <sub>P-P</sub>
Group Delay Variation over $f_C \pm 6.35$ MHz	GDV			23	200	ns <sub>P-P</sub>
Rejection 100 to $f_C - 10.3$ and $f_C + 10.3$ to $f_C + 100$ MHz		1, 2, 3	38	45		dB
Operating Temperature Range	$T_A$	1	-40		+85	°C
Differential Input and Output Impedance	250 ohms					
Case Style		6	SMP-03-S 7 x 5 mm Nominal Footprint			
Lid Symbolization (YY=year, WW=week, S=shift) See note 4			RFM SF1143B-4 YYWWSS			

**Electrical Connections**

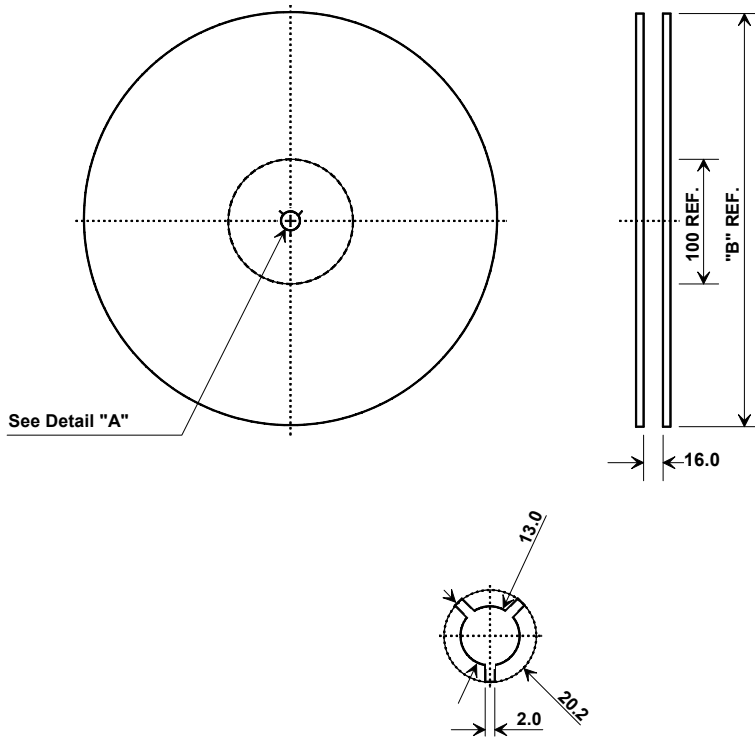
Connection	Port 1 Hot	Port 1 Ground Return or Hot	Port 2 Hot	Port 2 Ground Return or Hot	Case Ground
<b>Terminals</b>	10	1	5	6	All Others

**CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.**

**NOTES:**

1. Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50  $\Omega$  and measured with 50  $\Omega$  network analyzer.
2. Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency,  $f_C$ .
3. Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details.
4. "LRIP" or "L" after the part number indicates "low rate initial production" and "ENG" or "E" indicates "engineering prototypes."
5. The design, manufacturing process, and specifications of this filter are subject to change.
6. Tape and Reel Standard ANSI / EIA 481.
7. Either Port 1 or Port 2 may be used for either input or output in the design. However, impedances and impedance matching may vary between Port 1 and Port 2, so that the filter must always be installed in one direction per the circuit design.
8. US and international patents may apply.
9. Murata, stylized Murata logo, and Murata N.A., Inc. are registered trademarks of Murata Manufacturing Co., Ltd.

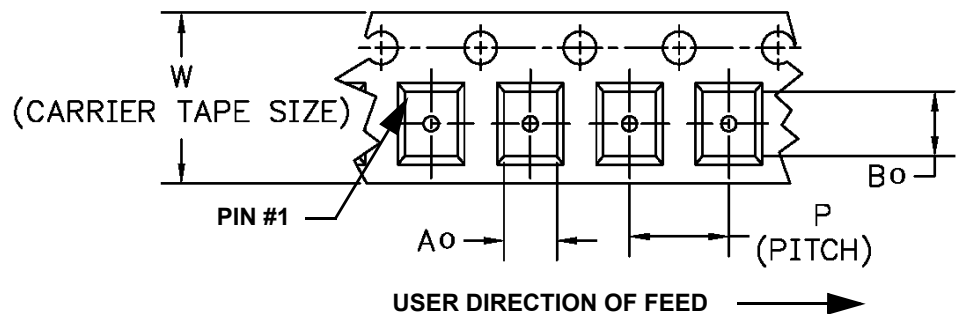
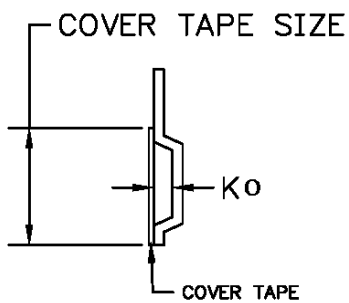
## Tape and Reel Specifications



"B" Nominal Size		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	2000

## COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions		Tolerance
Ao	5.5 mm	± 0.1mm
Bo	7.5 mm	± 0.1mm
Ko	2.0 mm	± 0.1mm
Pitch	8.0 mm	± 0.1mm
W	16.0 mm	± 0.2mm

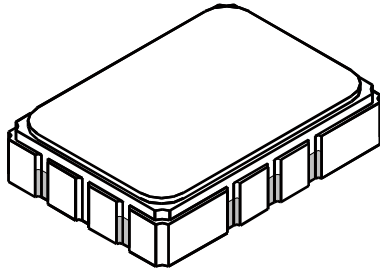


# SMP-03-S Case



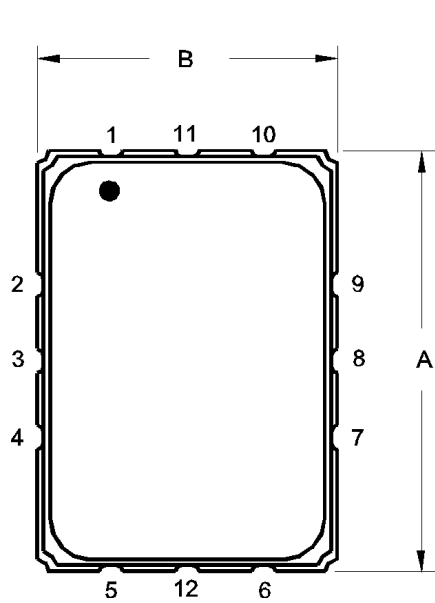
## 12-Terminal Ceramic Surface-Mount Case

5 x 7 mm Nominal Footprint

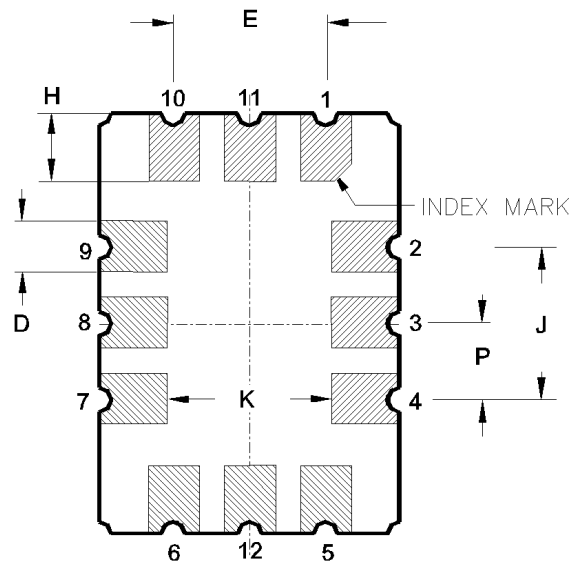
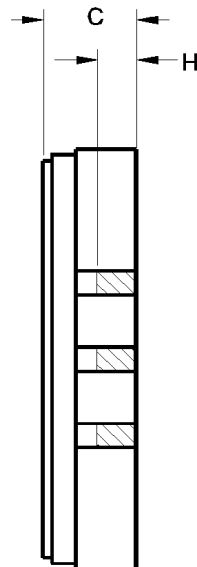


Case Dimensions						
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	6.80	7.00	7.20	0.268	0.276	0.283
B	4.80	5.00	5.20	0.189	0.197	0.205
C		1.65	2.00		0.065	0.079
D		0.80				
E	2.41	2.54	2.67	0.095	0.100	0.105
H	0.87	1.1	1.13	0.034	0.039	0.044
J		2.54				
K	2.87	3.00	3.13	0.113	0.118	0.123
P	1.14	1.27	1.40	0.045	0.050	0.055

Materials	
Solder Pad Termination	Au plating 30 - 60 μinches (76.2-152 μm) over 80-200 μinches (203-508 μm) Ni.
Lid	Fe-Ni-Co Alloy Electroless Nickel Plate (8-11% Phosphorus) 100-200 μinches Thick
Body	Al <sub>2</sub> O <sub>3</sub> Ceramic
Pb Free	



TOP VIEW



BOTTOM VIEW